

Kulicke & Soffa Industries, Inc.

## **Kulicke & Soffa Introduces New Offering at SEMICON West 2016**

SINGAPORE--(BUSINESS WIRE)-- Kulicke & Soffa Industries, Inc. (NASDAQ: KLIC) ("Kulicke & Soffa", "K&S" or the "Company"), announced today that it will be showcasing newly launched equipment and market leading packaging solutions at the SEMICON West 2016 trade show in San Francisco, California, from July 12 to 14, 2016.

Continuing with the successful launch of the Asterion™ wedge bonder, K&S will be introducing the Asterion™ EV - an extended version of the wedge bonder which is built on a new architecture with enhanced capability to handle a multitude of interconnect materials.

The Asterion™ EV offers an expanded bond area with new robust pattern recognition capabilities and extremely tight process controls for advanced interconnect materials. These advanced features deliver heightened productivity, bonding quality and reliability. The enlarged bondable area enhances flexibility and reduces factory line integration costs.

In addition, K&S will be featuring the new TPR (Twin Placement Robot), which brings the placement accuracy of the Hybrid to 7µm. The Hybrid is a multi-application solution for advanced packaging, ideal for wafer level packaging, Fan-Out Wafer Level Packaging (FOWLP), System-in-Package (SiP), Multi-Chip Module (MCM), flip-chip, modules and embedded components. It is highly capable of placing both active and passive components, achieving a throughput up to 27 kUPH for Flip Chips plus 48 kUPH for passives with a single machine.

Chan Pin Chong, Kulicke & Soffa's Vice President for the Wedge Bonders, Capillaries and Blades Business Lines, said, "K&S is continuing to partner with customers in different application spaces to develop innovative offerings of latest products and solutions. These technical solutions further strengthen our position as a comprehensive solution provider to the market."

Customers can view these technical solutions at the SEMICON West 2016 trade show in San Francisco, California, Booth #6060 from July 12-14, 2016.

### **About Kulicke & Soffa**

Kulicke & Soffa (NASDAQ: KLIC) is a global leader in the design and manufacture of semiconductor, LED and electronic assembly equipment. As a pioneer in this industry, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions and organic development, adding advanced packaging, advanced SMT, wedge bonding and a broader range of expendable tools to its core ball bonding products. Combined with its extensive expertise in process technology, K&S is well positioned to help customers meet the challenges of assembling the next-generation semiconductor and LED devices. ([www.kns.com](http://www.kns.com))

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